



# SOT669

plastic, single-ended surface-mounted package; 4 terminals;  
4.9 mm x 4.45 mm x 1 mm body

9 January 2017

Package information

## 1. Package summary

<b>Dimensions (mm)</b>	4.9 x 4.45 x 1
<b>Terminal position code</b>	S (single)
<b>Package type descriptive code</b>	LFPAK56; Power-SO8
<b>Package outline version code</b>	SOT669
<b>Manufacturer package code</b>	SOT669
<b>Package type industry code</b>	LFPAK56; Power-SO8
<b>Package outline version description</b>	plastic, single-ended surface-mounted package; 4 terminals; 4.9 mm x 4.45 mm x 1 mm body
<b>Package style descriptive code</b>	SMS (surface-mounted single in-line)
<b>Package body material type</b>	P
<b>JEDEC package outline code</b>	MO-235
<b>Handling precautions</b>	IC26_CHAPTER_3_2000
<b>Thermal design considerations</b>	SC18_1999_CHAPTER_5_2
<b>Mounting method type</b>	S (surface mount)
<b>Generic mounting and soldering information</b>	SC18_2004_CHAPTER_4_3
<b>Reflow soldering footprint</b>	sot669_fr
<b>Package life cycle status</b>	REL
<b>Major version date</b>	18-9-2008
<b>Minor version date</b>	14-5-2012
<b>Security status</b>	COMPANY PUBLIC
<b>Modified date</b>	22-11-2012
<b>Issue date</b>	27-2-2013
<b>Web publication date</b>	28-11-2012
<b>Initial web publication date</b>	10-3-2011
<b>Customer specific indicator</b>	N
<b>Maturity</b>	Preliminary
<b>Package author</b>	Nair Deepa
<b>Package approver</b>	Nair Deepa

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A <sub>2</sub>	package height	0.95	-	1	1.1	mm
A	seated height	1.01	-	1.1	1.2	mm
D	package length	3.8	-	3.95	4.1	mm



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Symbol	Parameter		Min	Typ	Nom	Max	Unit
E	package width		4.8	-	4.9	5	mm
e	nominal pitch		-	-	-	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	4	-	

## 2. Package outline

Plastic single-ended surface-mounted package (LFPAK56; Power-SO8); 4 leads SOT669

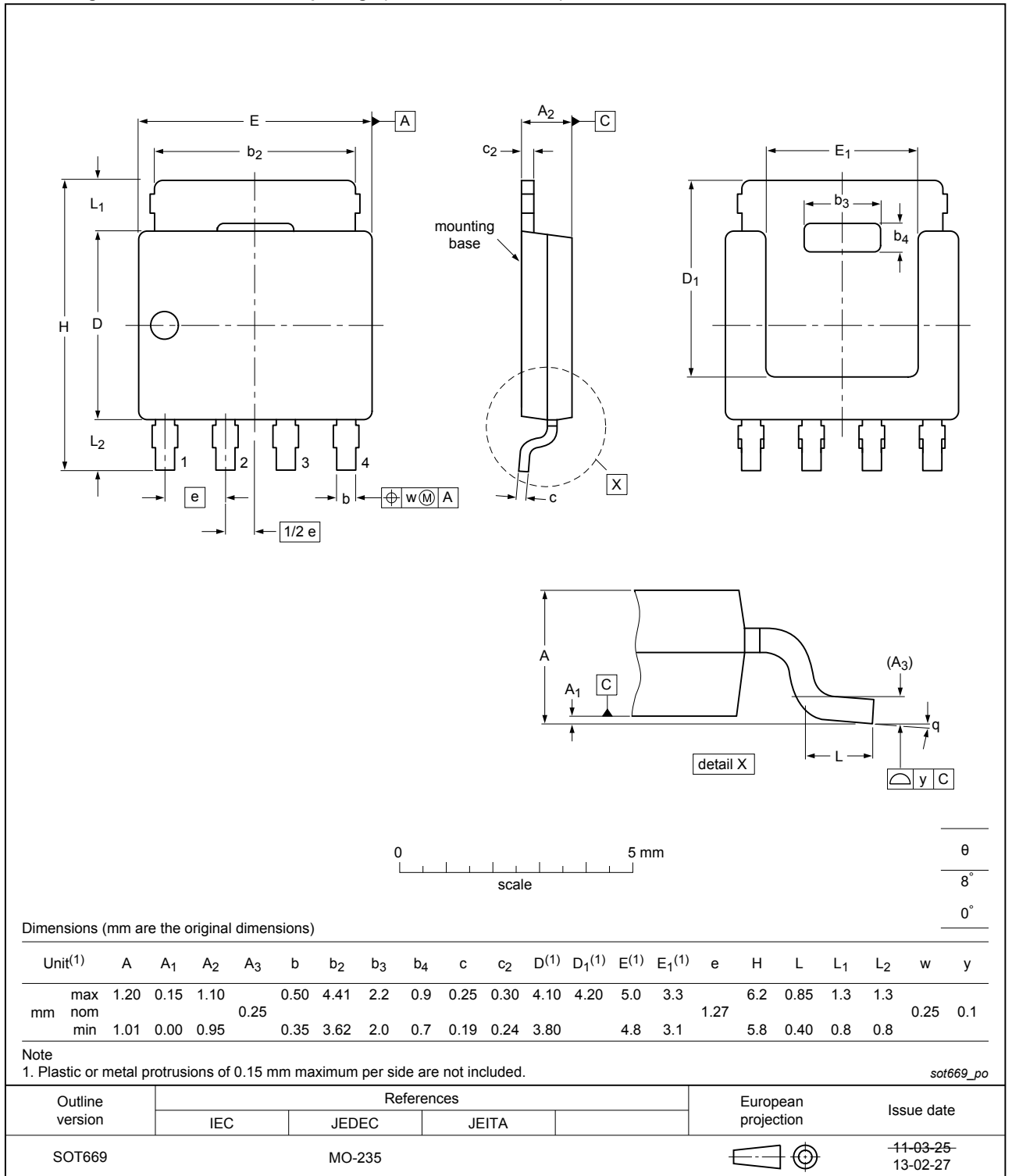


Fig. 1. Package outline LFPAK56; Power-SO8 (SOT669)

### 3. Soldering

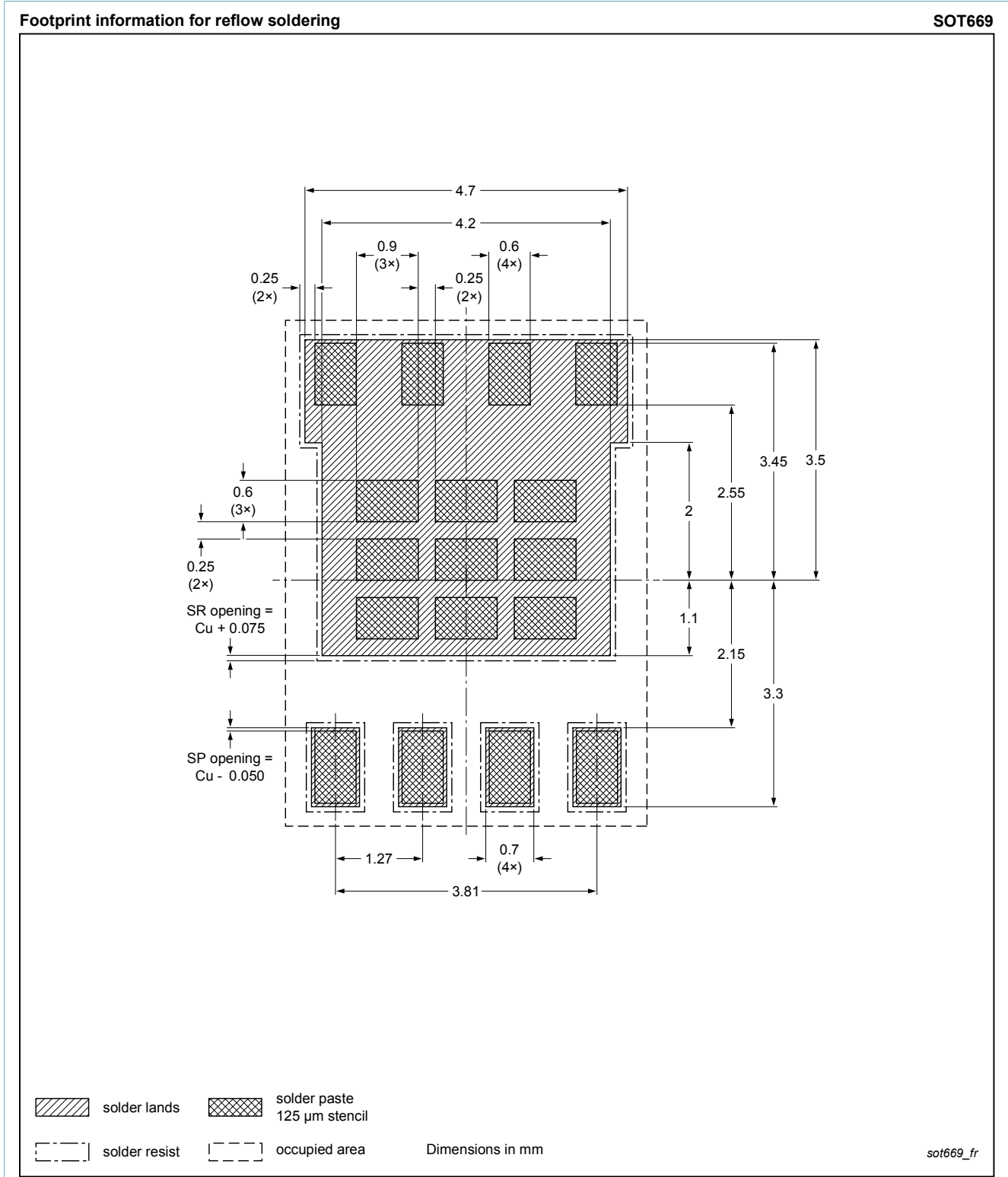
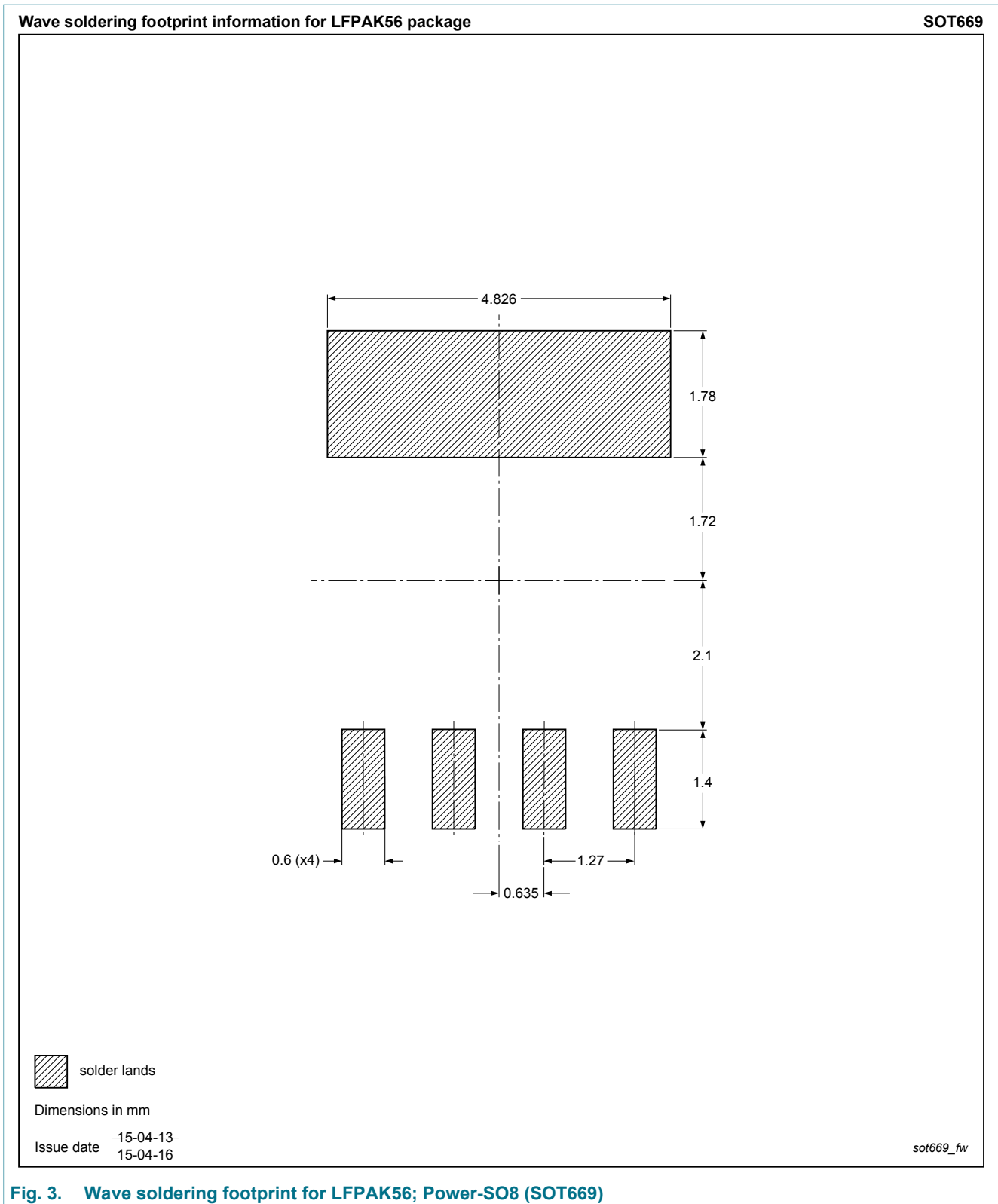


Fig. 2. Reflow soldering footprint for LFPAK56; Power-SO8 (SOT669)



## 4. Legal information

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